



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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MS2272

RF AND MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

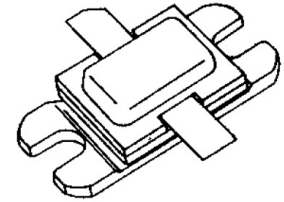
Features

- 255 MHz BANDWIDTH
- GOLD METALLIZATION
- EMITTER SITE BALLASTED
- $P_{OUT} = 350W$ MINIMUM
- $G_P = 7.6$ dB
- LOW THERMAL RESISTANCE
- INPUT/OUTPUT MATCHING
- 15:1 VSWR CAPABILITY

DESCRIPTION:

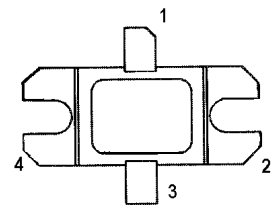
The MS2272 avionics power transistor is a broadband, high peak pulse power device specifically designed for avionics applications requiring broad bandwidth with moderate duty cycle and pulse width constraints such as ground/ship DME/TACAN.

The MS2272 is also designed for specialized applications where reduced power is provided under pulse formats utilizing short pulse widths and high burst or overall duty cycles. This device is capable of withstanding 15:1 VSWR mismatch load conditions at any phase angle under full rated conditions.



.400 x .500 2LFL (M216)
hermetically sealed

PIN CONNECTION



- | | |
|--------------|------------|
| 1. Collector | 3. Emitter |
| 2. Base | 4. Base |

ABSOLUTE MAXIMUM RATINGS ($T_{CASE} = 25^{\circ}C$)

Symbol	Parameter	Value	Unit
P_{DISS}	Power Dissipation*	940	W
I_C	Device Current*	24	A
V_{CC}	Collector-Supply Voltage*	50	
T_J	Junction Temperature (RF Pulsed Operation)	+200	$^{\circ}C$
T_{STG}	Storage Temperature	- 65 to + 200	$^{\circ}C$

THERMAL DATA

$R_{TH(j-c)}$	Junction-Case Thermal Resistance*	0.16	$^{\circ}C/W$
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*Applies only to rated RF amplifier operation

ELECTRICAL SPECIFICATIONS (T_{CASE} = 25°C)

STATIC

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
BV _{CBO}	I _C = 50 mA I _E = 0 mA	65	----	----	V
BV _{EBO}	I _E = 15 mA I _C = 0 mA	3.0	----	----	V
BV _{CER}	I _C = 50 mA R _{BE} = 10 Ω	65	----	----	V
I _{CES}	V _{CE} = 50 V	----	----	30	mA
h _{FE}	V _{CE} = 5 V I _C = 5A	10	----	---	----

DYNAMIC

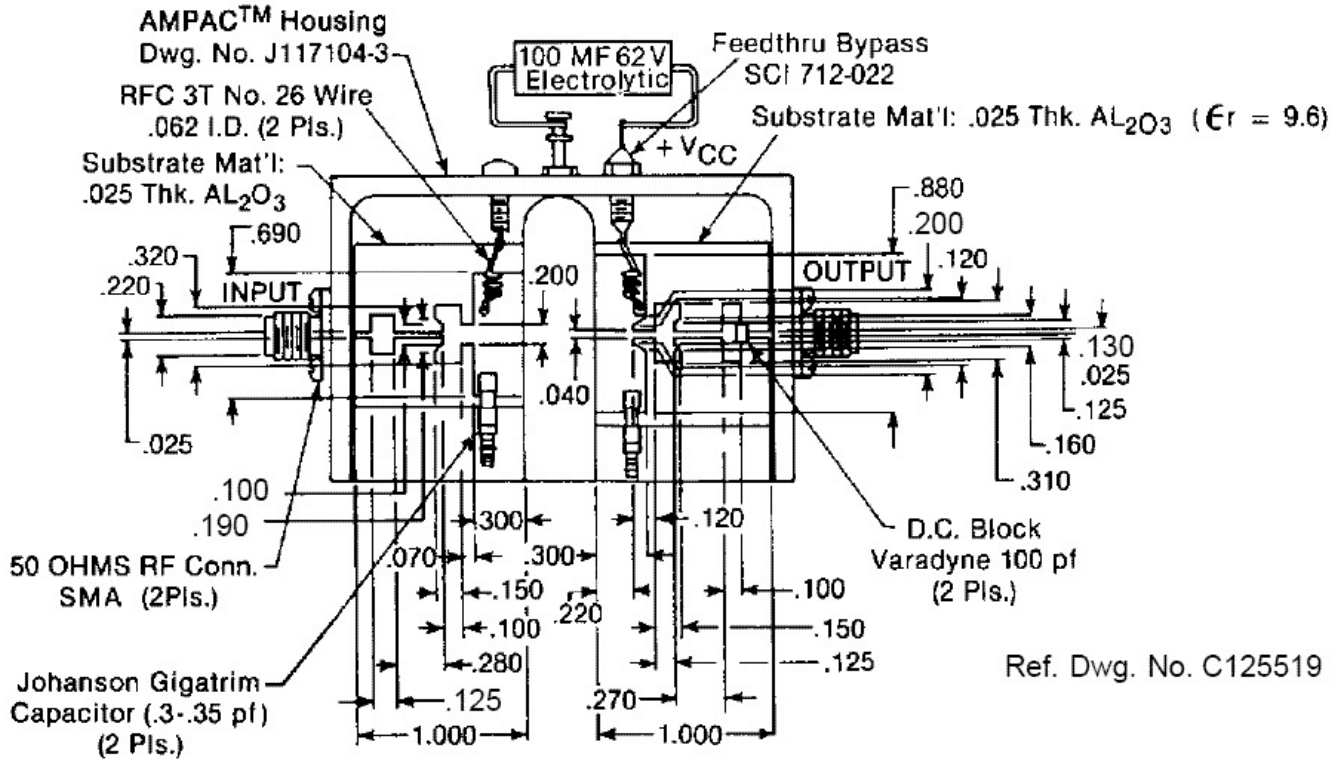
Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
P _{OUT}	f = 960 - 1215 MHz P _{IN} = 60 W V _{CC} = 50 V	350	----	----	W
η _C	f = 960 - 1215 MHz P _{IN} = 60 W V _{CC} = 50 V	38	----	----	%
G _P	f = 960 - 1215 MHz P _{IN} = 60 W V _{CC} = 50 V	7.6	----	----	dB

Note: Pulse Format: 10 μS
 Duty Cycle: 10%

IMPEDANCE DATA

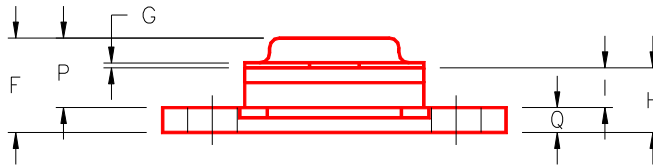
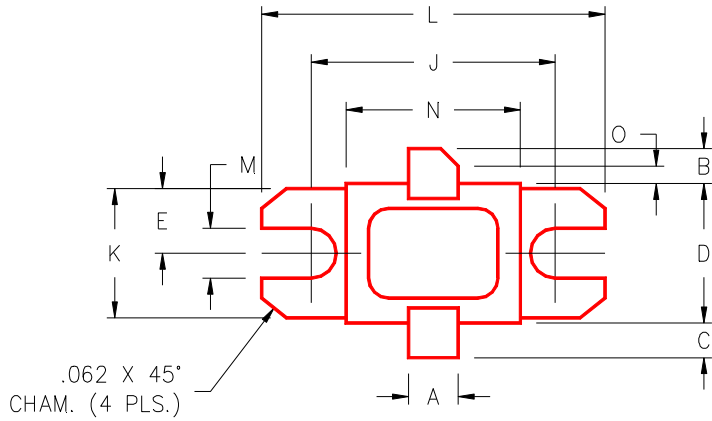
FREQ	Z _{IN} (Ω)	Z _{CL} (Ω)
960 MHz	2.0 + j3.6	1.7 - j2.2
1090 MHz	3.5 + j1.7	2.0 - j1.7
1215 MHz	1.6 + j0.5	1.8 - j2.0

TEST CIRCUIT



PACKAGE MECHANICAL DATA

PACKAGE STYLE M216



	MINIMUM INCHES/MM	MAXIMUM INCHES/MM		MINIMUM INCHES/MM	MAXIMUM INCHES/MM
A	.140/3,56		J	.700/17,78	
B	.110/2,80		K	.386/9,80	
C	.110/2,80		L	.900/22,86	
D	.395/10,03	.407/10,34	M	.120/3,05	
E	.193/4,90		N	.500/12,70	
F		.230/5,84	O	.050/1,27	
G	.003/0,08	.006/0,15	P		.170/4,32
H	.118/3,00	.131/3,33	Q	.062/1,58	
I	.063/1,60				